PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		● ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Assembly Location Code Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXXX XX-COO YYWWNNN	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator
		● ATMEL XXXXXXXX XXXXYYWW# XXXX-X XXXXXX AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Class, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXXX XXX-COO XXXXXX YYWWNNN	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator
24 / 32 / 40 / 44 / 48	VQFN 5X5 MM	● XXXXXX XXXXXX AAAAAA X YYWW	**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Subcon Code, Date Code ● = Pin 1 indicator	● XXXXXX XXXXXX YYWWNNN CC YYWW	**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Country of Origin, Date Code ● = Pin 1 indicator
		● XXXXXXXX AAAAAA.# X YYWW	**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Date Code	● XXXXXXXX YYWWNNN CCYYWW	**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code
		● ATMEL XXXXXXXX XXXXXX YYWW#-X AAAAAA OR ● ATMEL XXXXXXXX XXX YYWW#-X AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) Line 5 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXX XX-COO XXXXXX YYWWNNN OR ● ATMEL XXXXXx XXX-COO XXXXXX YYWWNNN	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator

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Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
		● ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, MRL (if shown in ABI) Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXXX XX-COO YYWWNNN	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator
40	VQFN 6X6 MM	● ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXXX XX-COO YYWWNNN	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator
48	VQFN 6X6 MM	Atmel XXXXXXX XXXXXX YYWWX X AAAAAA **ARM** ●	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	Atmel XXXXXXX XXXXXX YYWW X YYWWNNN **ARM** ●	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
		● ATMEL XXXXXXXXX XXXX-X YYWW AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator	● ATMEL XXXXXXX XX-COO YYWWNNN	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator

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Atmel				MICROCHIP	
Lead/Pin/ Bump Count	**Package Description**	**Pre-Change_Marking Diagram (Atmel)**	**Pre-Change_Marking Guidelines (Atmel)**	**Post-Change_Marking Diagram (Microchip)**	**Post-Change_Marking Guidelines (Microchip)**
44 / 64	VQFN 7X7 MM	ATMEL XXXXXXXX XXXXYYWW# XXXX-X XXXXXX AAAAAA	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Country of Assembly, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability ● = Pin 1 indicator	XXXXXXX XXX-COO XXXXXX YYWWNNN	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark
48	VQFN 7X7 MM	Atmel XXXXXXXXX XX YYWWX X AAAAAA ARM	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	Atmel XXXXXXXXX XX YYWW X YYWWNNN ARM	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
64	VQFN 7.5X7.5 MM	LIMES XXXXXXXXXXX YYWWX X AAAAAA XXXXXXXXXXXXX YYWWX X AAAAAA	**Top Mark** Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability ● = Pin 1 indicator **Top Mark** Line 1= Device Name Line 2 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability ● = Pin 1 indicator	LIMES XXXXXXXXXXX YYWW X YYWWNNN XXXXXXXXXXXXX YYWW X YYWWNNN	**Top Mark** Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Design Revision Line 5 = Lot Traceability ● = Pin 1 indicator **Top Mark** Line 1= Device Name Line 2 = Date Code, Design Revision Line 5 = Lot Traceability ● = Pin 1 indicator

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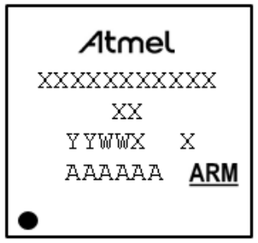
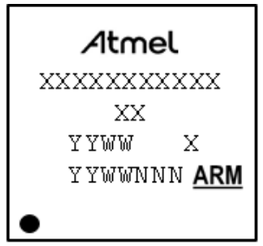
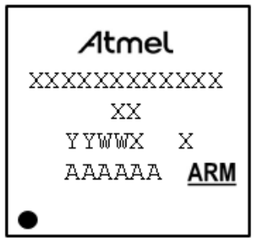
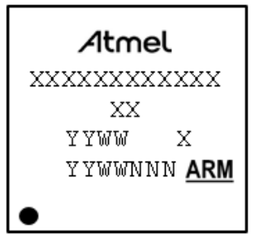
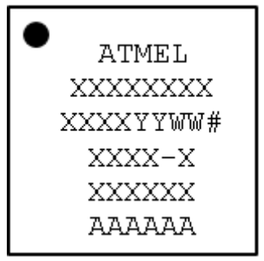
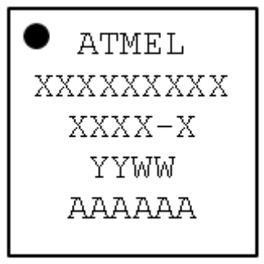
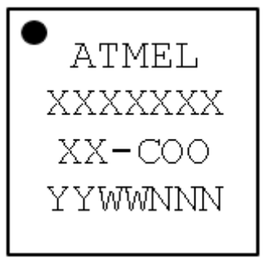
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
64	VQFN 9X9 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) Line 4 = Country of Assembly, Assembly Location Code Line 5 = Die ID, Revision Line 6 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Assembly Location Code Line 4 = Date Code Line 5 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Class, Die Revision, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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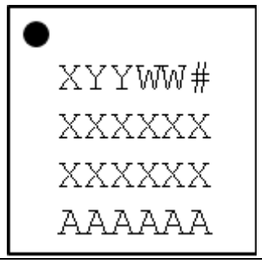
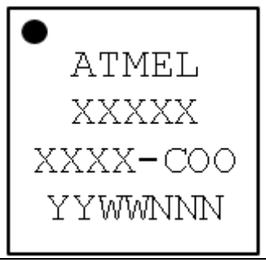
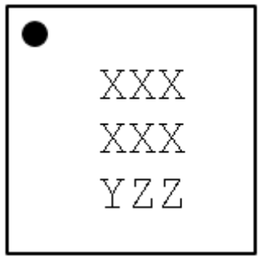
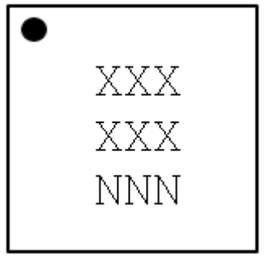
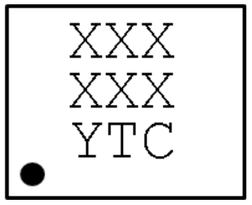
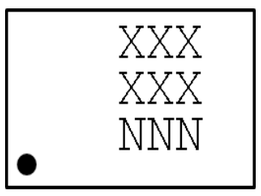
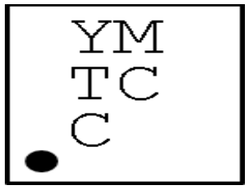
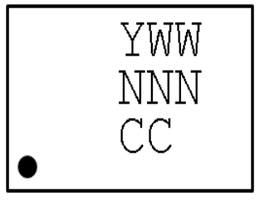
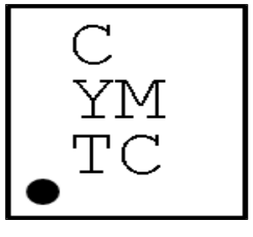
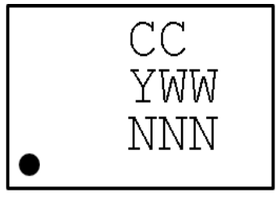
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
20	WQFN 4X4 MM		**Top Mark** Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name (shortened) Line 3 = Device Information Line 4 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= ATMEL Line 2 = Device Name (shortened) Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator
8	UDQFN 2X2 MM		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability ● = Pin 1 indicator
8	UDFN 2X3 MM		**Top Mark** Line 1= Truncation Code Line 2 = Device Information Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Truncation Code Line 2 = Device Information Line 3 = Lot Traceability ● = Pin 1 indicator
			**Top Mark** Line 1= Year, Month Line 2 = Lot Traceability Line 3 = Subcon Code		**Top Mark** Line 1= Date Code Line 2 = Lot Traceability Line 3 = Country Code
8	XDFN / UDFN		**Top Mark** Line 1= Subcon Code Line 2 = Year, Month Line 3 = Lot Traceability		**Top Mark** Line 1= Country of Origin Line 2 = Date Code Line 3 = Lot Traceability

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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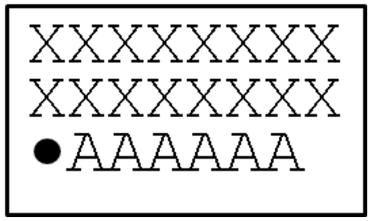
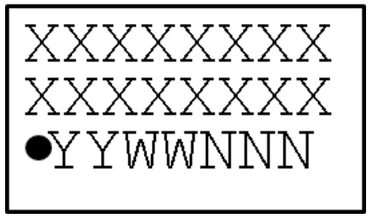
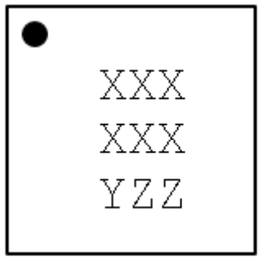
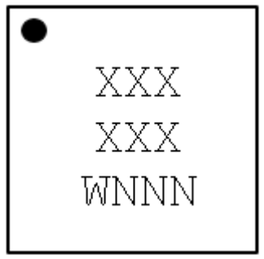
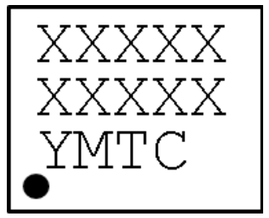
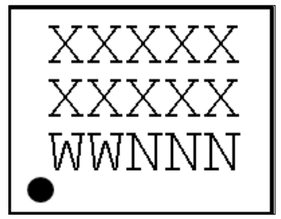
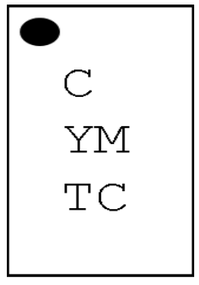
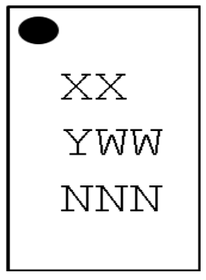
Atmel				MICROCHIP	
Lead/Pin/ Bump Count	**Package Description**	**Pre-Change_Marking Diagram (Atmel)**	**Pre-Change_Marking Guidelines (Atmel)**	**Post-Change_Marking Diagram (Microchip)**	**Post-Change_Marking Guidelines (Microchip)**
8	UDFN 6X5 MM		**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator
10	VDFN 3X3 MM		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark
2	XSFN (DFN 5X3.5 MM)		**Top Mark** Line 1= ATML Line 2 = Truncation Code, Device Information Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= ATML Line 2 = Truncation Code, Device Information, Year Line 3 = Lot Traceability ● = Pin 1 indicator
3	LAB (DFN 2.5X6.5 MM)		**Top Mark** Line 1= Subcon Code Line 2 = Year, Month Line 3 = Trace Code ● = Pin 1 indicator		**Top Mark** Line 1= Country of Origin Line 2 = Date Code Line 3 = Lot Traceability ● = Pin 1 indicator

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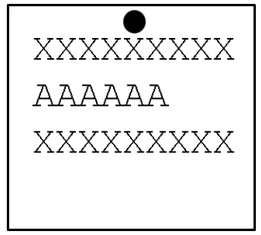
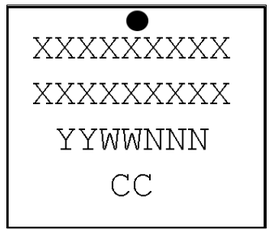
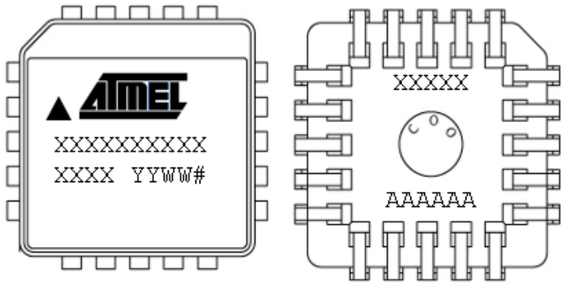
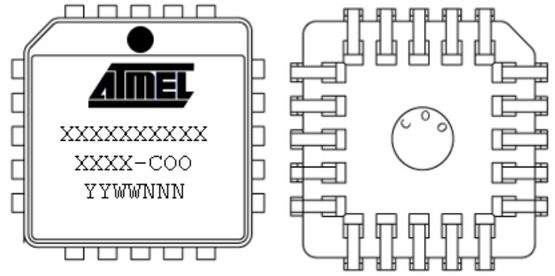
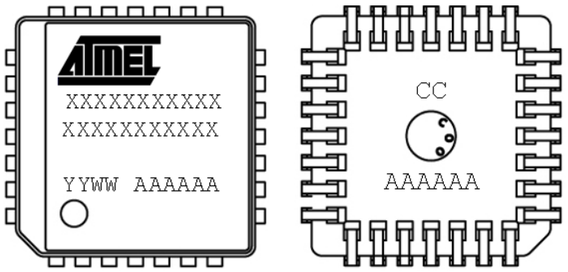
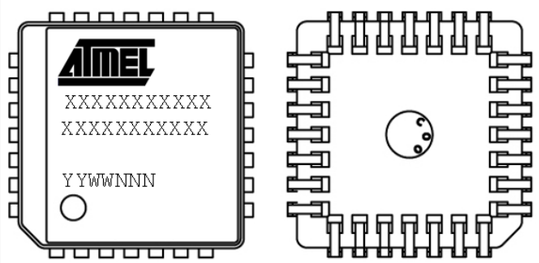
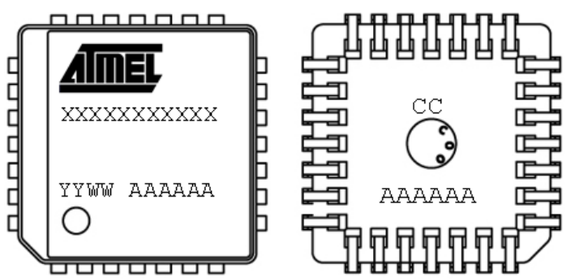
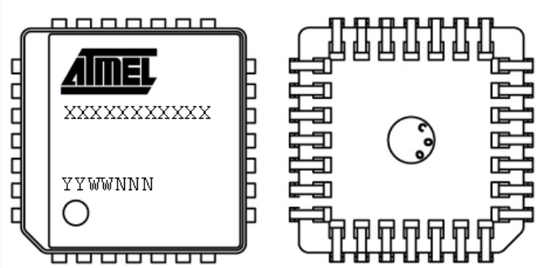
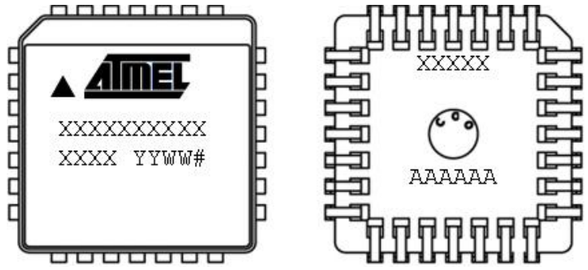
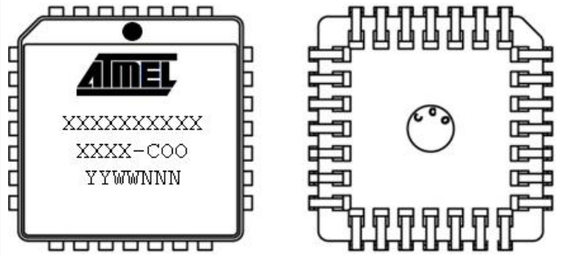
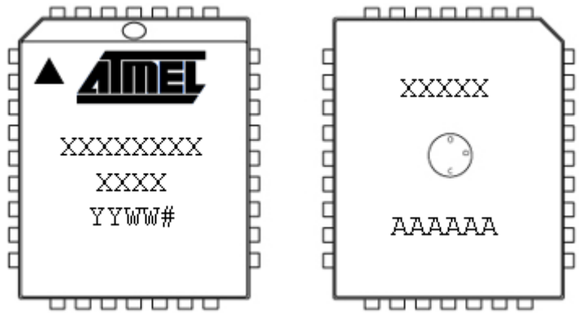
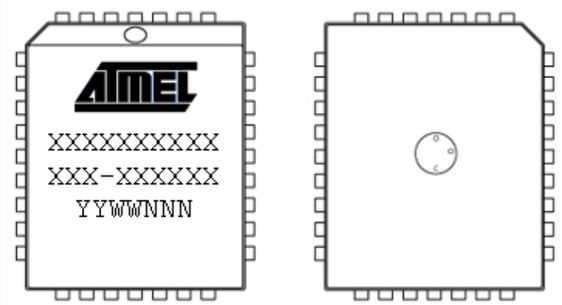
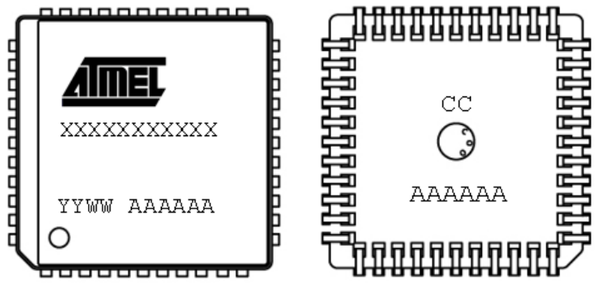
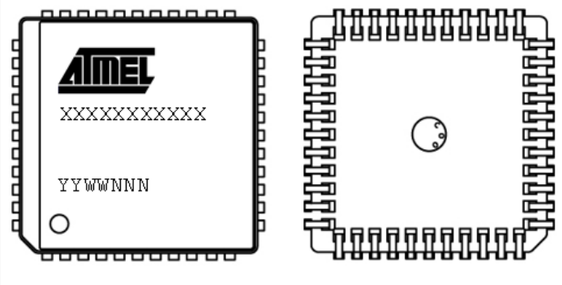
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
20	PLCC		**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code ● = Pin 1 indicator		**Top Mark** Line 1= Device Name Line 2 = Device Information, Date Code Line 3 = Lot Traceability Line 4 = Country of Origin ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
28	PLCC		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

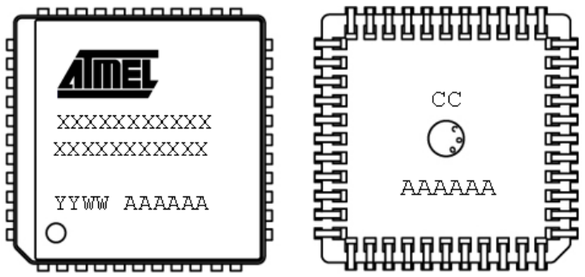
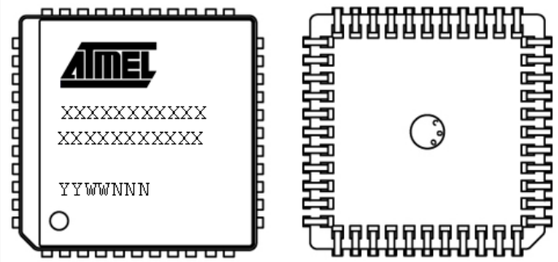
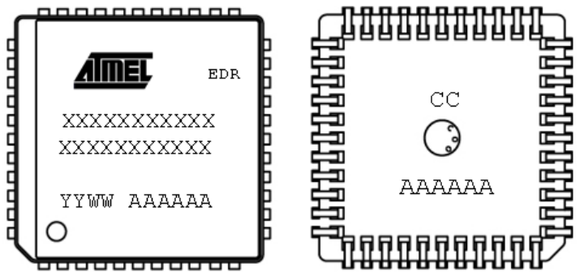
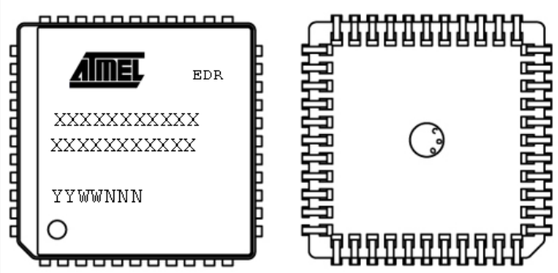
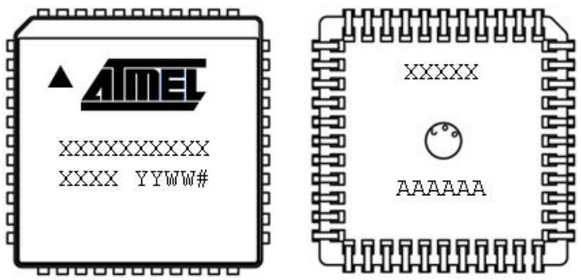
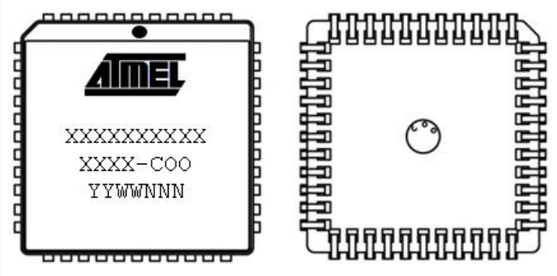
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
32	PLCC		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
44	PLCC		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

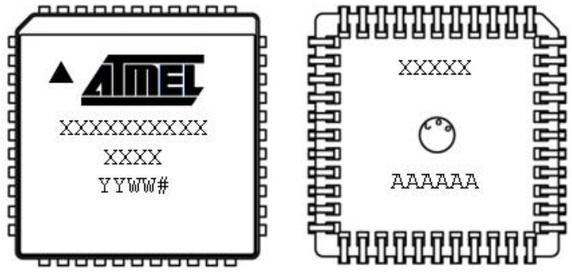
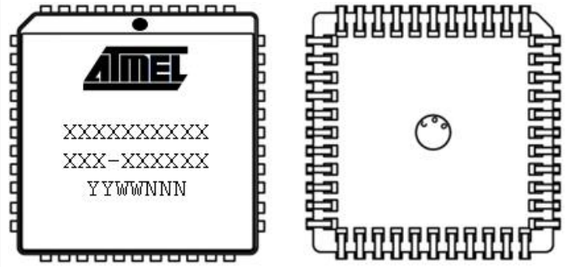
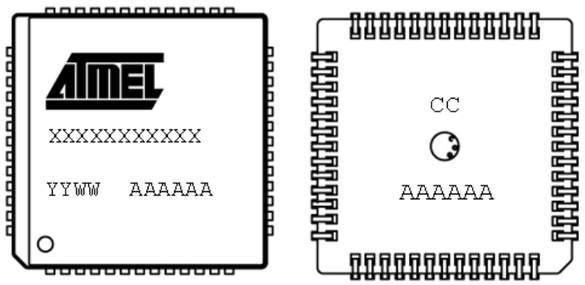
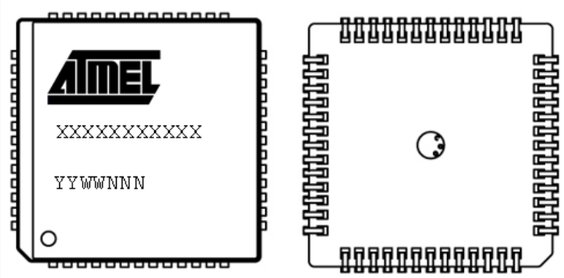
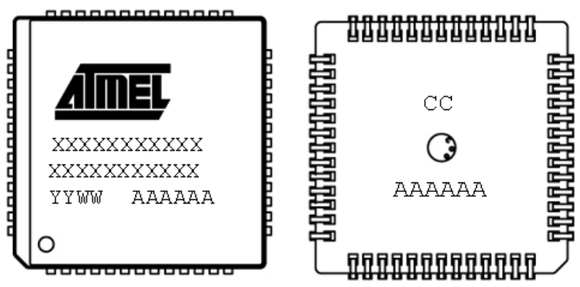
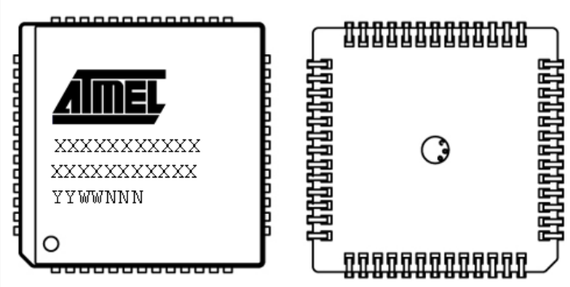
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Atmel Logo, EDR Line 2 = Silicon Revision Line 3 = Device Name Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo, EDR Line 2 = Silicon Revision Line 3 = Device Name Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country or Origin Line 4 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

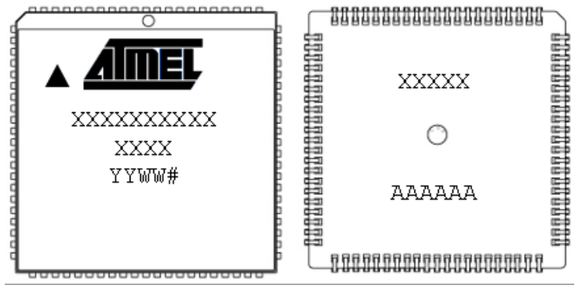
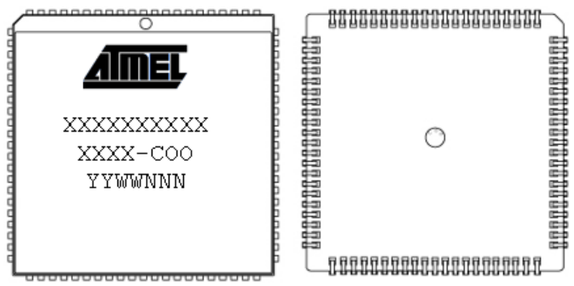
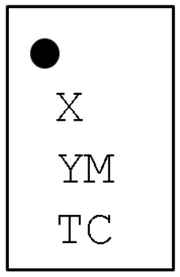
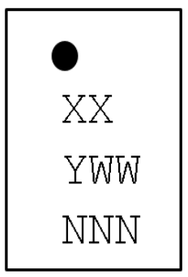
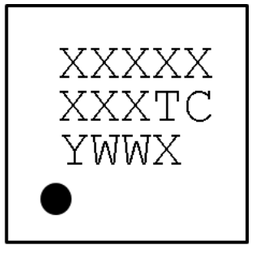
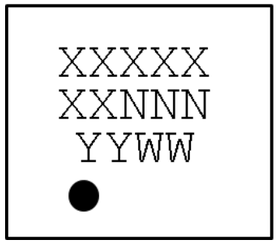
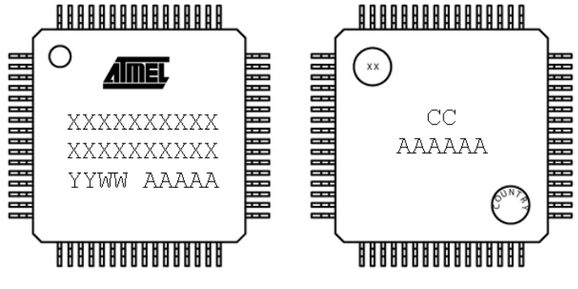
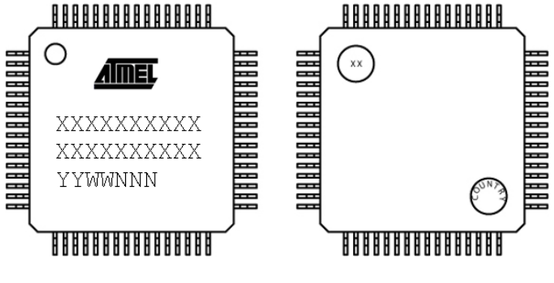
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
52	PLCC		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
84	PLCC		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country or Origin Line 4 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
2	CONTACT (SIP MODULE - 4x2 MM)		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1=Country of Origin Line 2 = Date Code Line 3 = Lot Traceability ● = Pin 1 indicator
8	MSOP - 3x3 MM		**Top Mark** Line 1= Truncation Code Line 2 = Class Code, Trace Code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Truncation Code Line 2 = Class Code, Lot Traceability Line 3 = Date Code ● = Pin 1 indicator
32 / 48	LQFP		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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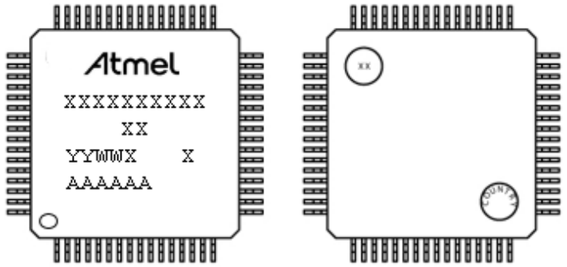
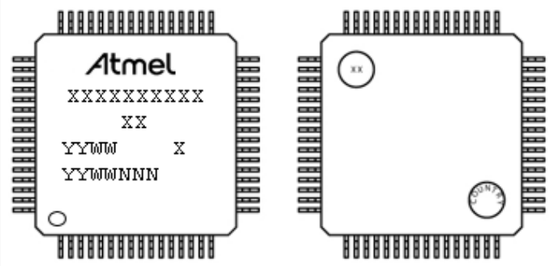
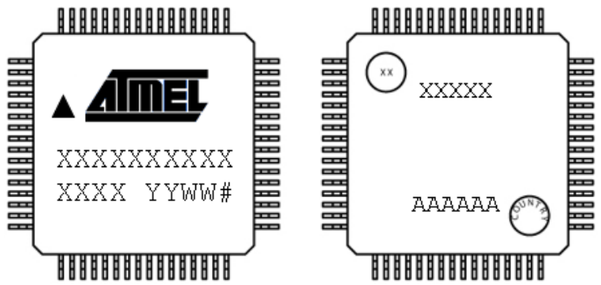
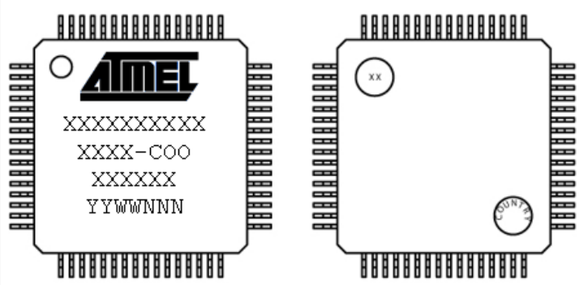
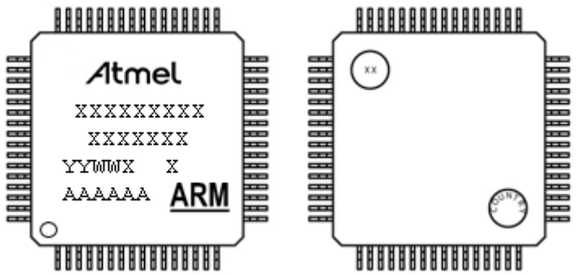
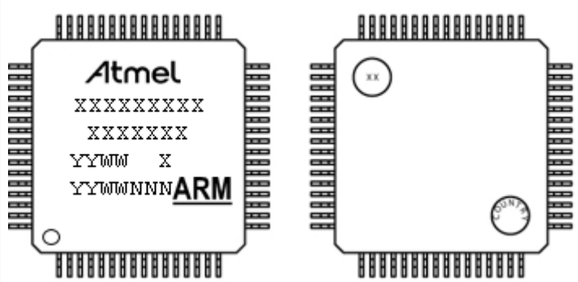
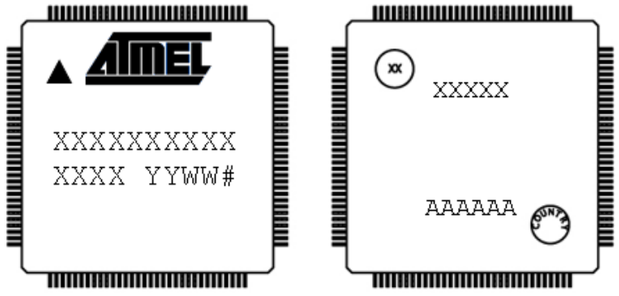
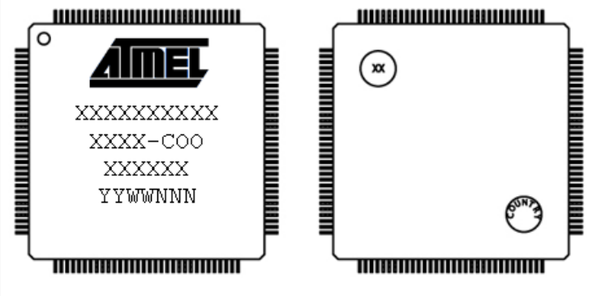
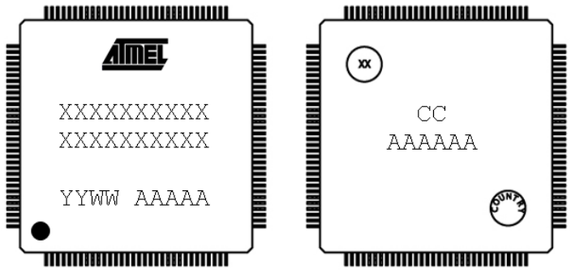
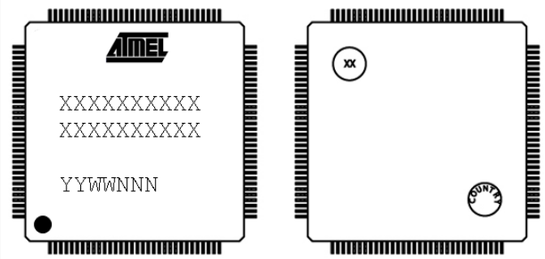
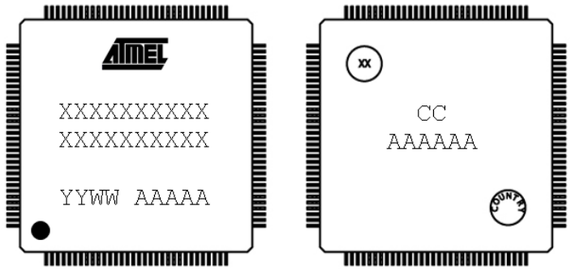
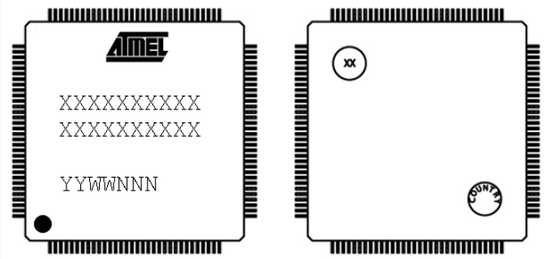
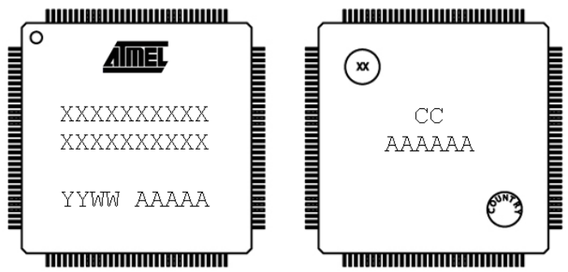
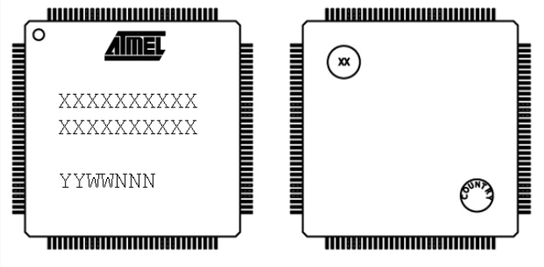
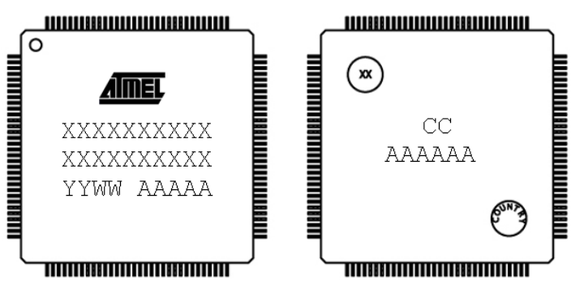
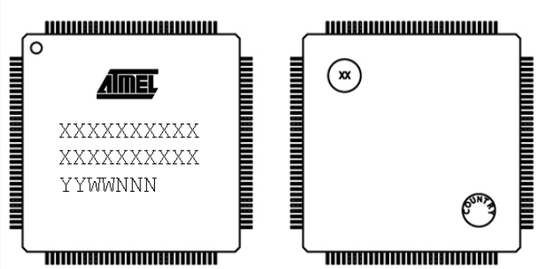
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
48	LQFP 7X7 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
44	LQFP 10X10 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability ● = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ●O = Pin 1 indicator **Bottom Mark** No bottom mark
64	LQFP 10X10 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability ● = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ●O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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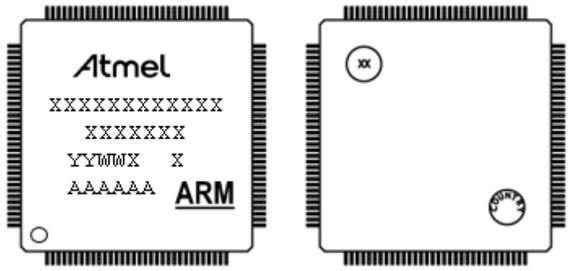
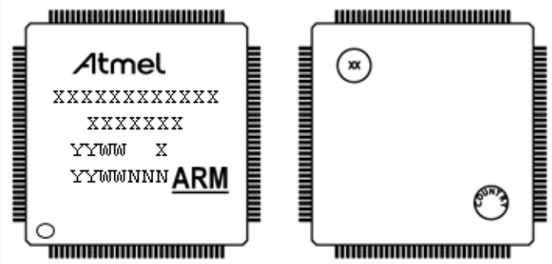
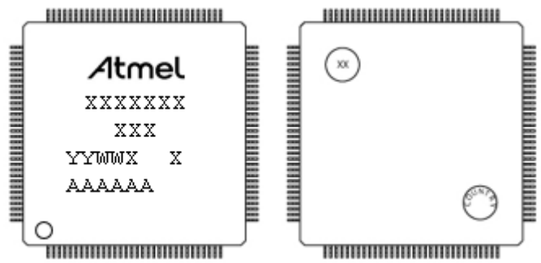
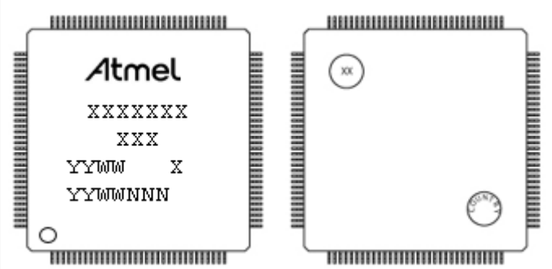
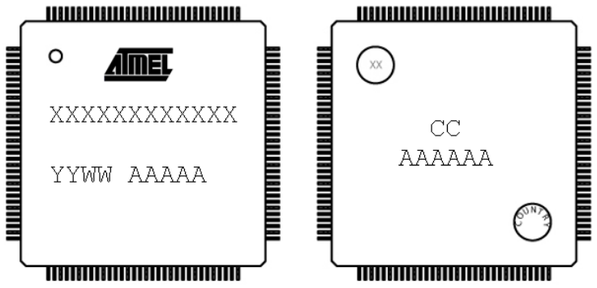
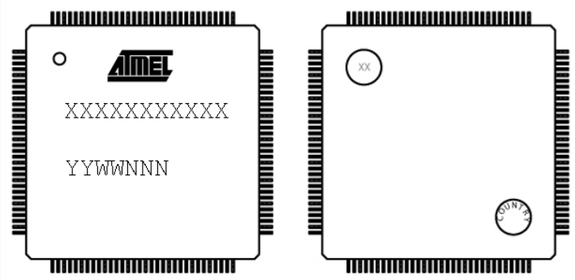
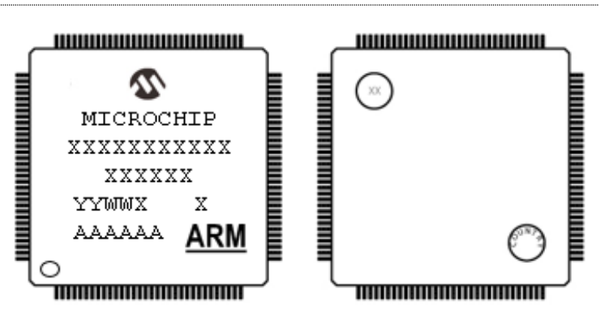
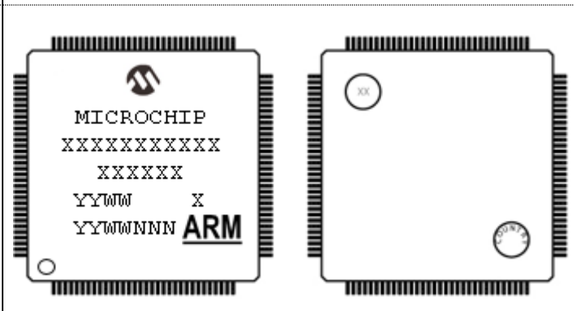
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
80	LQFP 12X12 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
100	LQFP 14X14 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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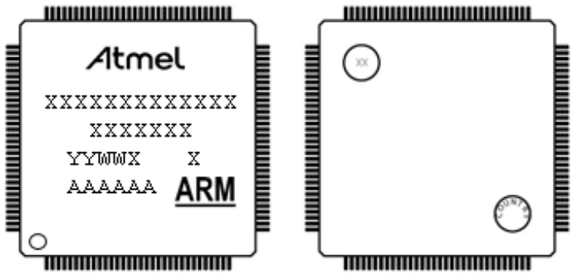
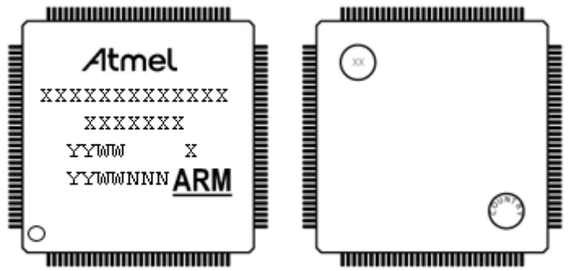
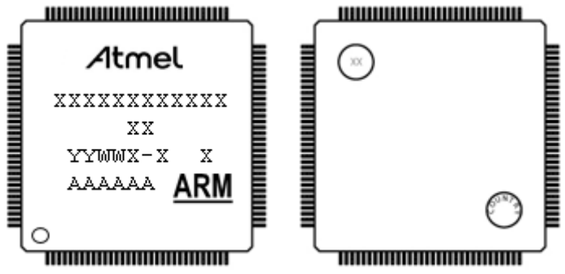
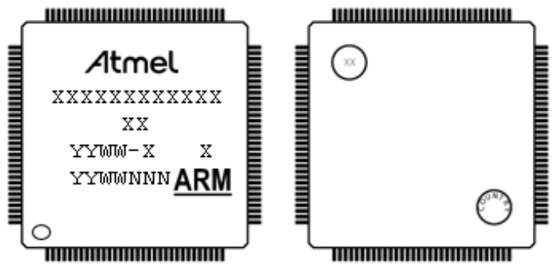
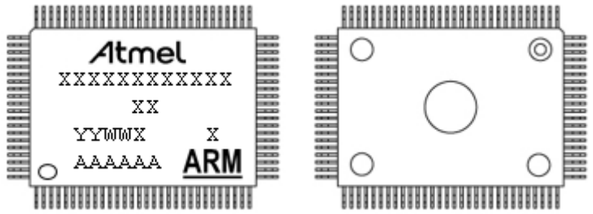
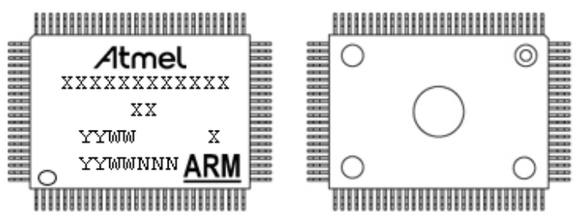
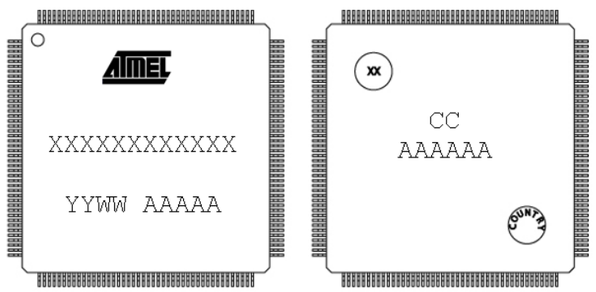
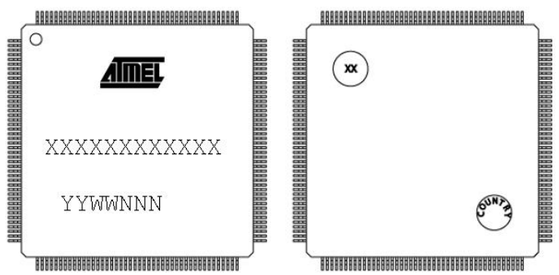
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
			OR **Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		OR **Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
128	LQFP 14X20 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
144	LQFP 20X20 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

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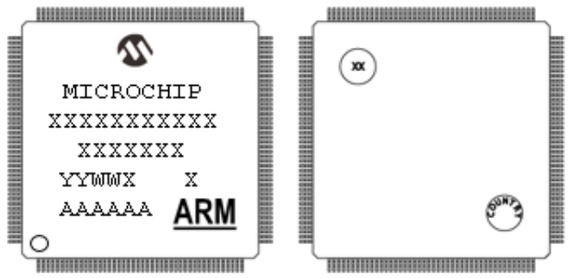
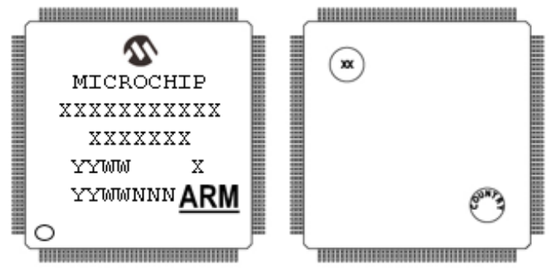
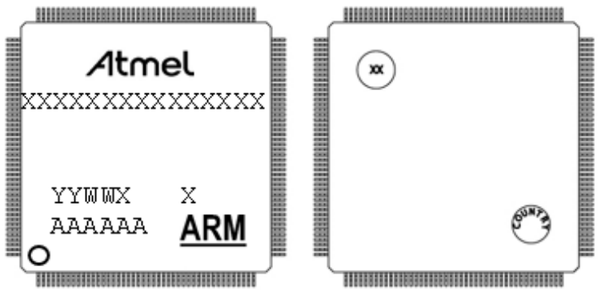
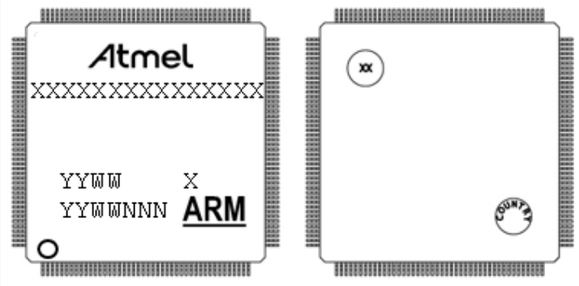
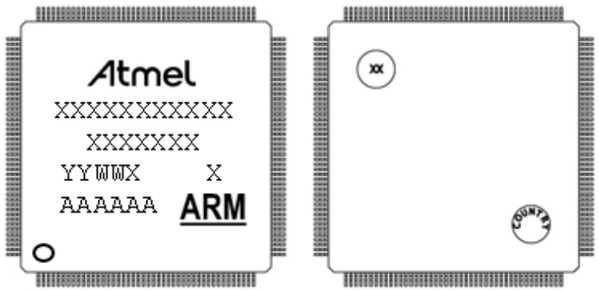
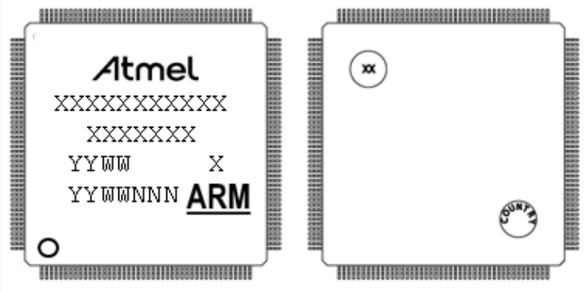
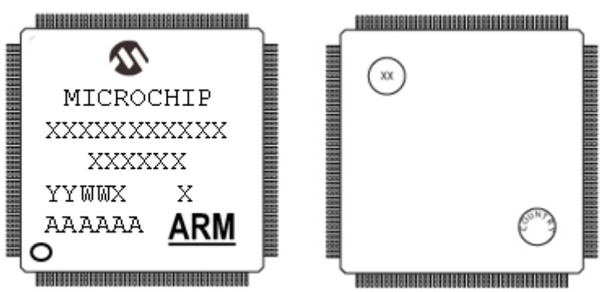
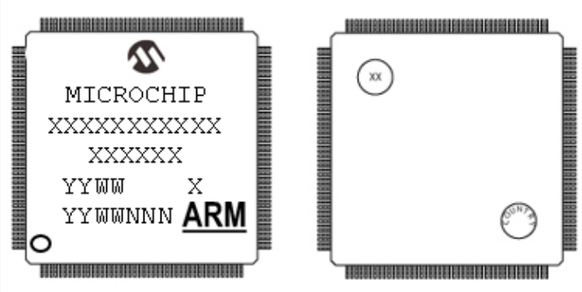
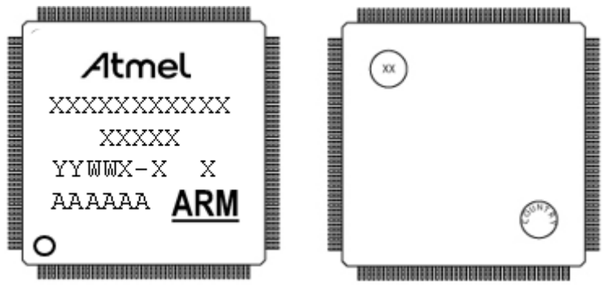
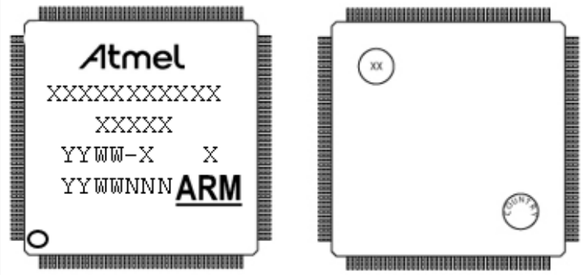
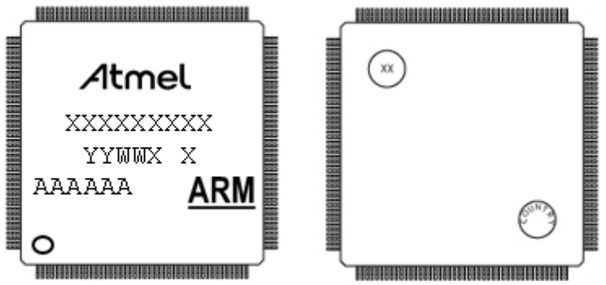
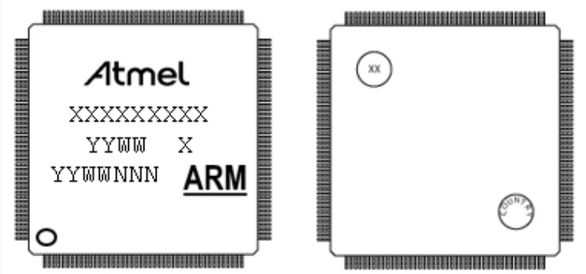
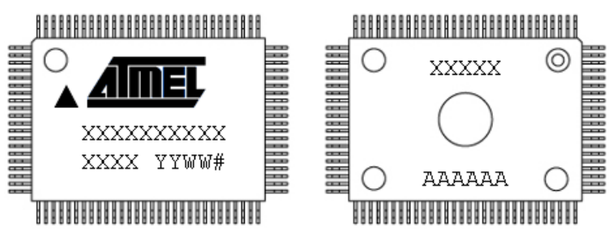
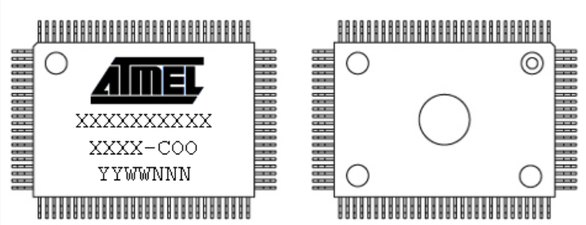
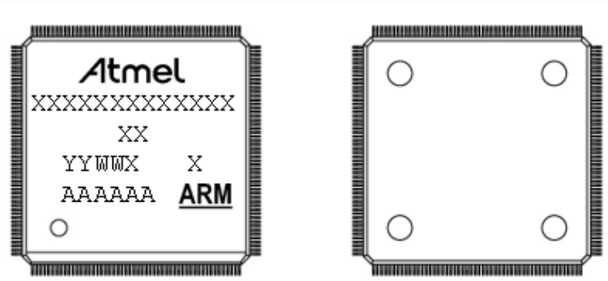
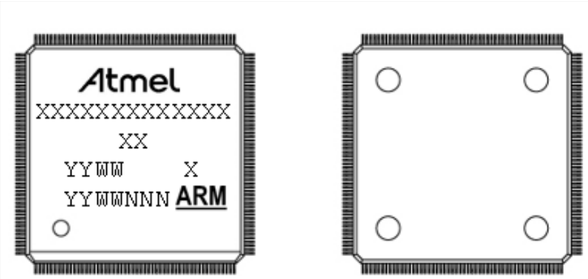
Atmel				MICROCHIP	
Lead/Pin/ Bump Count	**Package Description**	**Pre-Change_Marking Diagram (Atmel)**	**Pre-Change_Marking Guidelines (Atmel)**	**Post-Change_Marking Diagram (Microchip)**	**Post-Change_Marking Guidelines (Microchip)**
			**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
176	LQFP 24X24 MM		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark

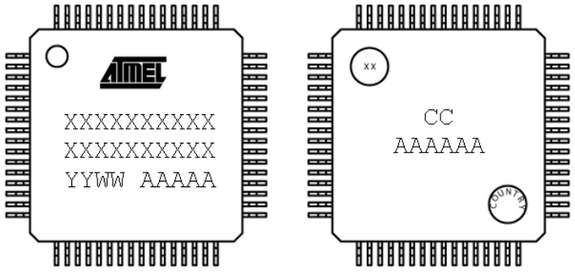
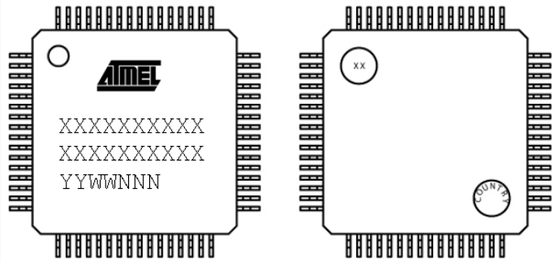
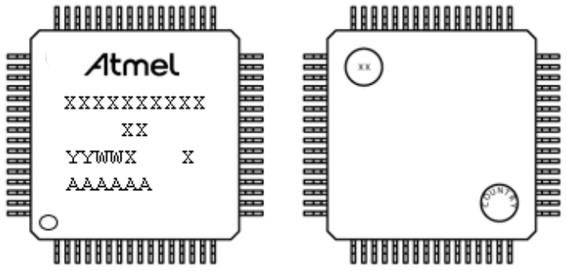
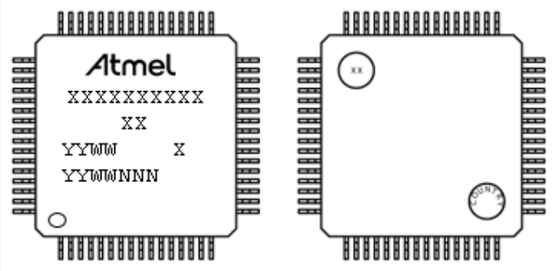
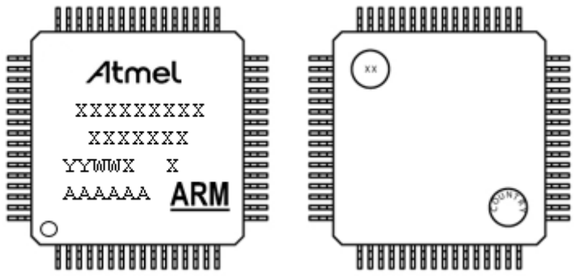
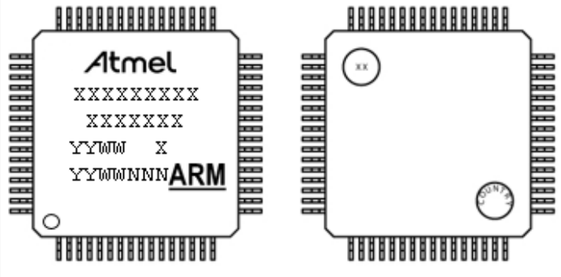
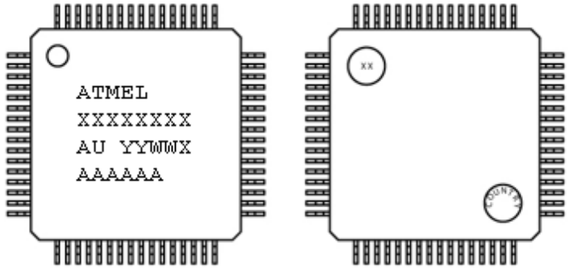
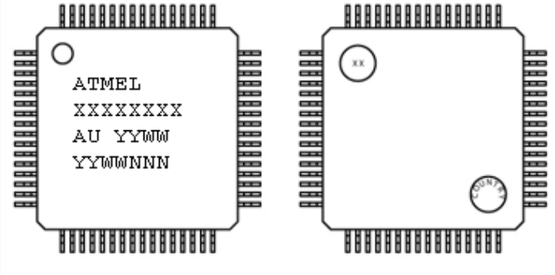
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark
100	PQFP 14X20 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) O = Pin 1 indicator ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
208	PQFP 28X28 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark

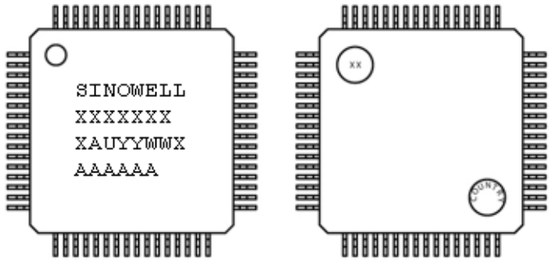
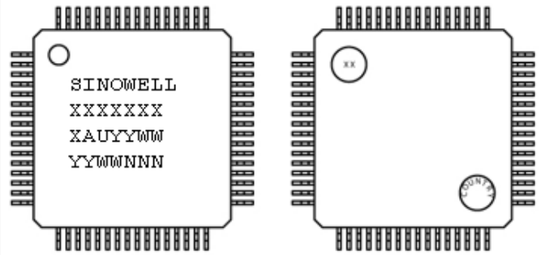
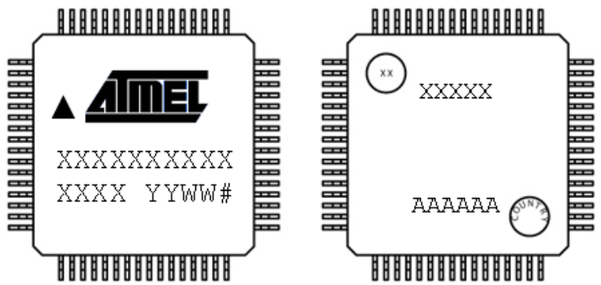
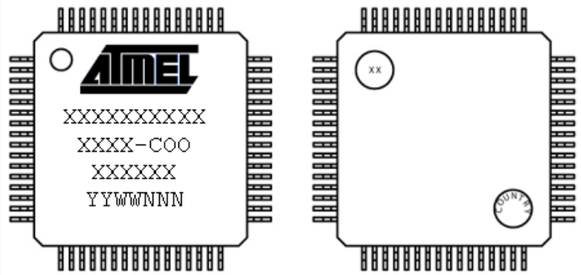
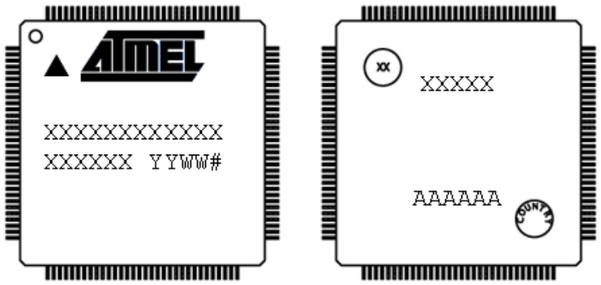
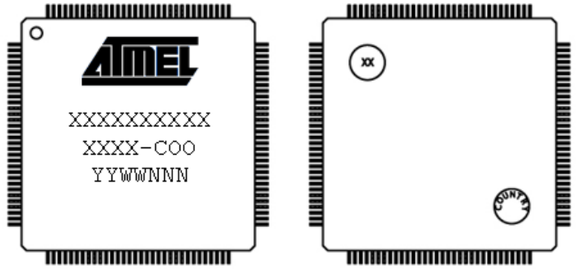
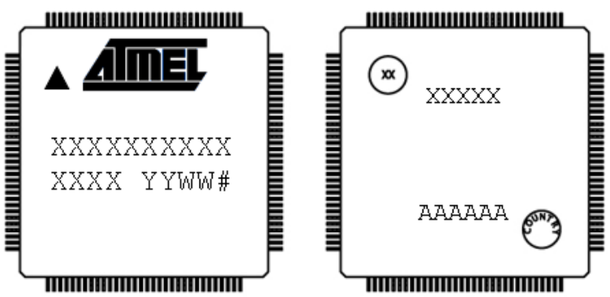
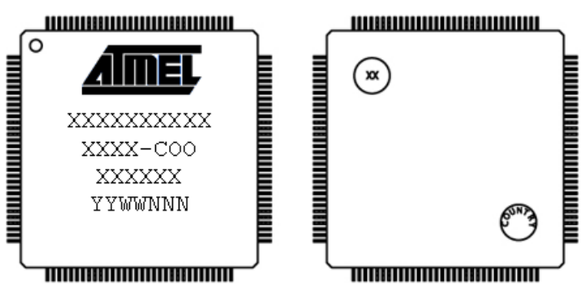
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
32 / 48	TQFP 7X7 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM O = Pin 1 indicator **Bottom Mark** No bottom mar
			**Top Mark** Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Date Code Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= SINOWELL Line 2 = Device Name Line 3 = Device Information, Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark		**Top Mark** Line 1= SINOWELL Line 2 = Device Name Line 3 = Device Information, Date Code Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
44	TQFP 10X10 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) O = Pin 1 indicator ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

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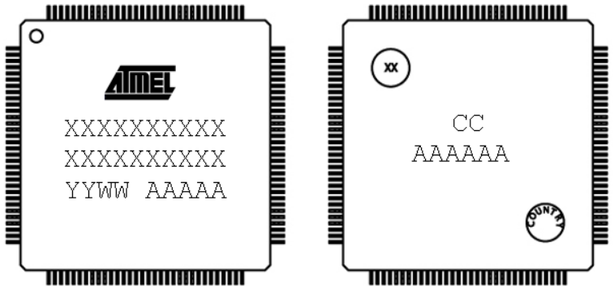
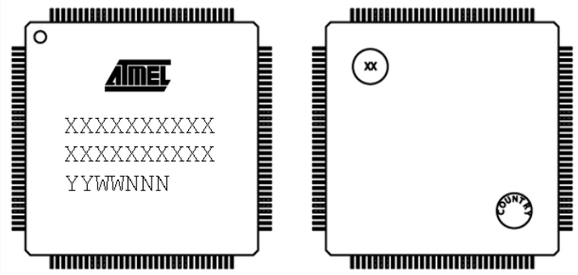
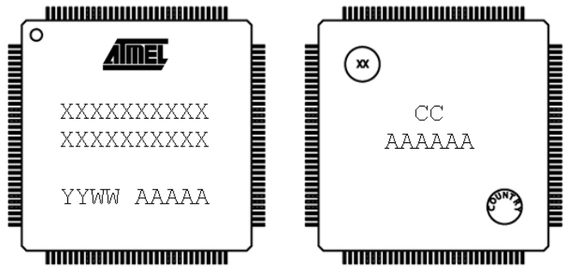
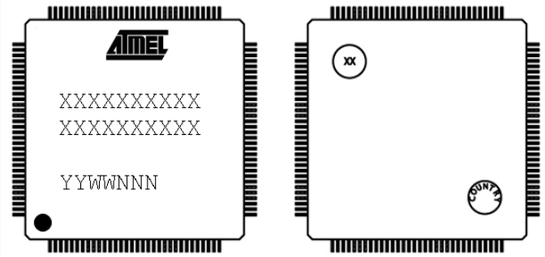
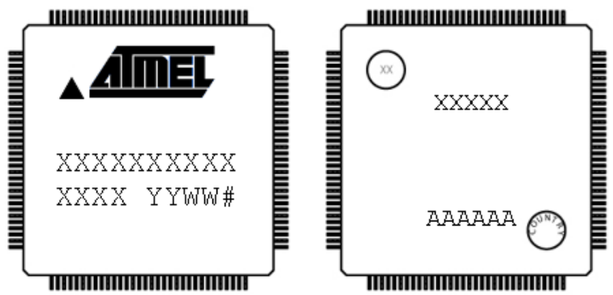
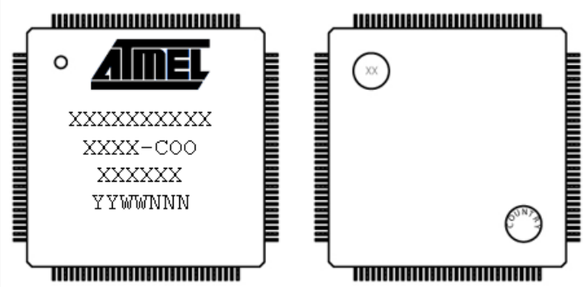
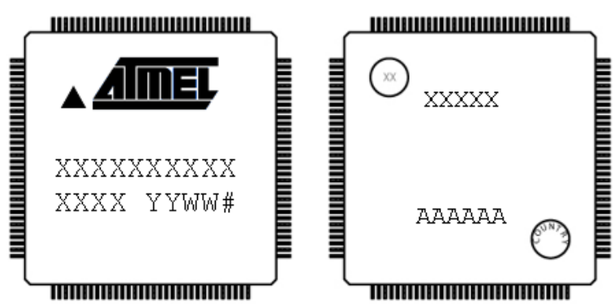
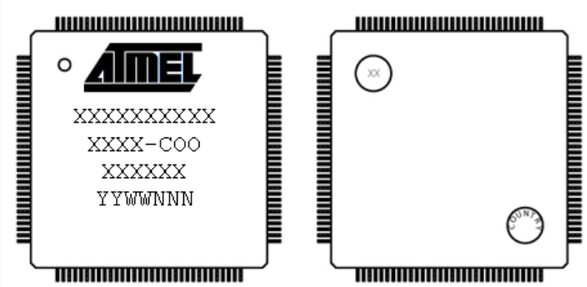
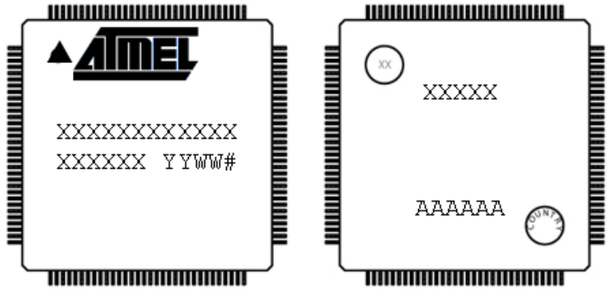
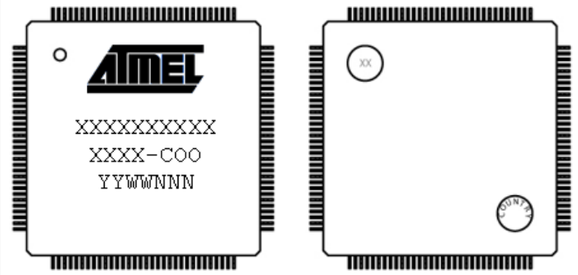
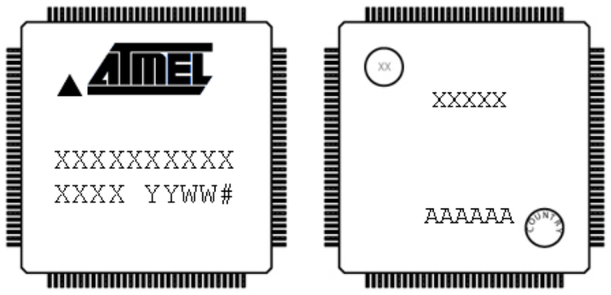
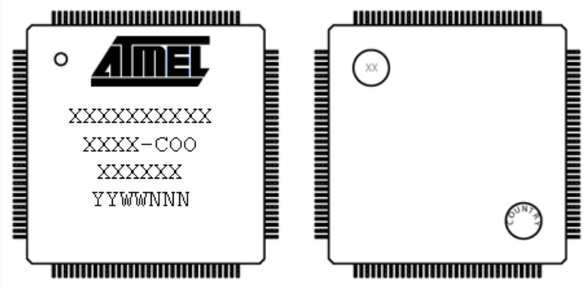
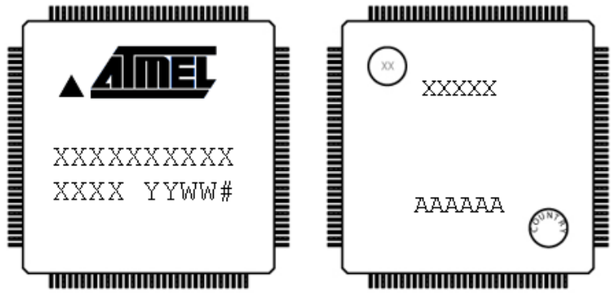
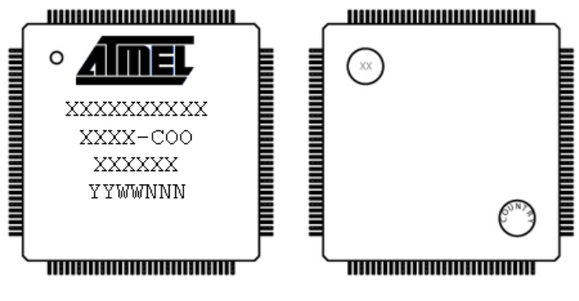
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
64	TQFP 10X10 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Lot Traceability ● = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ●O = Pin 1 indicator **Bottom Mark** No bottom mark
64	TQFP 14X14 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

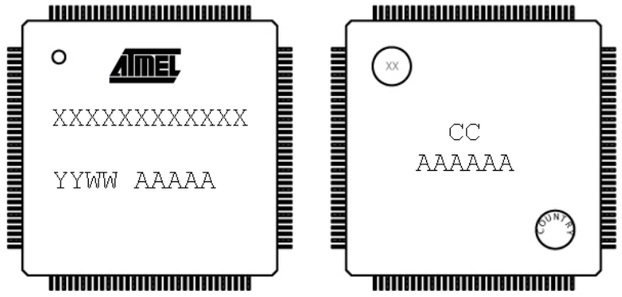
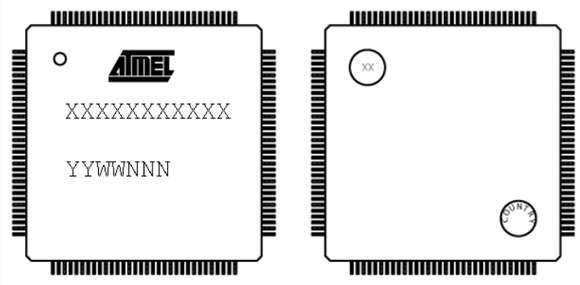
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
100	TQFP 14X14 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Atmel				MICROCHIP	
Lead/Pin/ Bump Count	**Package Description**	**Pre-Change_Marking Diagram (Atmel)**	**Pre-Change_Marking Guidelines (Atmel)**	**Post-Change_Marking Diagram (Microchip)**	**Post-Change_Marking Guidelines (Microchip)**
			**Top Mark** Line 1= Atmel Logo Line 2 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability